

#### Features

- DC - 2.0 GHz
- 250 Watts
- BeO Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- 100% Tested

#### General Specifications

<b>Resistive Element:</b>	Thick film
<b>Substrate:</b>	Beryllium oxide ceramic
<b>Cover:</b>	Alumina ceramic
<b>Mounting Flange:</b>	Copper, nickel plated per QQ-N-290
<b>Lead(s):</b>	99.99% pure silver (.005" thk)

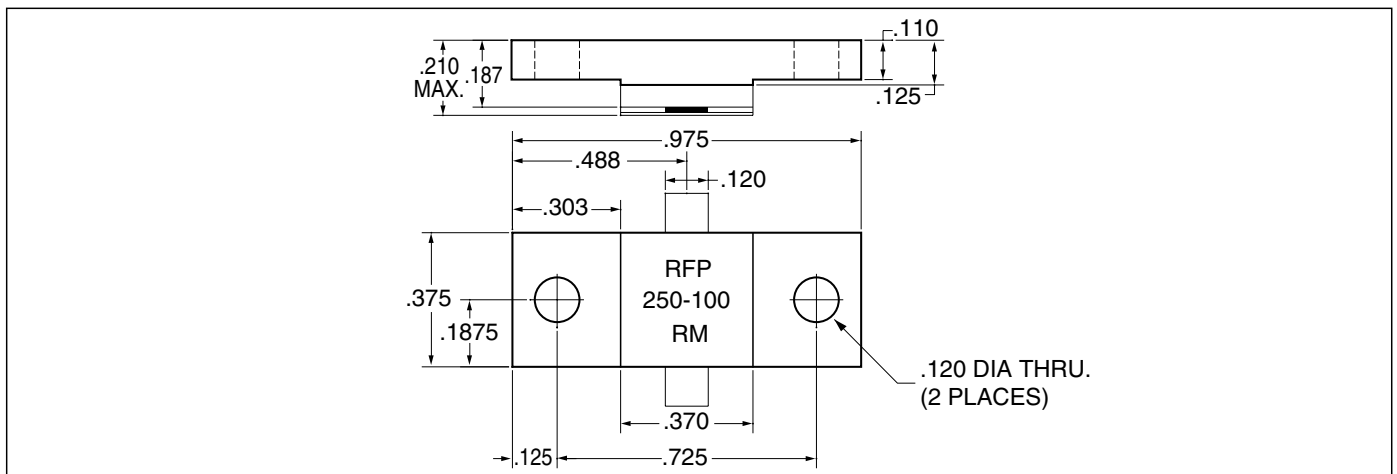
#### Electrical Specifications

<b>Resistance Value:</b>	100 ohms, $\pm 5\%$
<b>Frequency Range:</b>	DC - 2.0 GHz
<b>Power:</b>	250 Watts
<b>Capacitance:</b>	3.3 pF

**Notes:** Tolerance is  $\pm 0.10$ , unless otherwise specified. Operating temperature is  $-55^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$  (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. Lead length 0.15" minimum.

**Specifications subject to change without notice.**

#### Outline Drawing



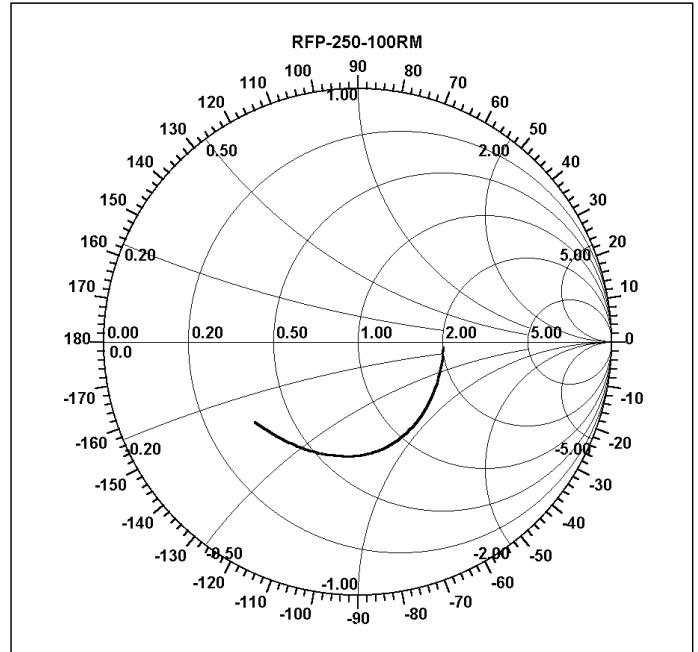
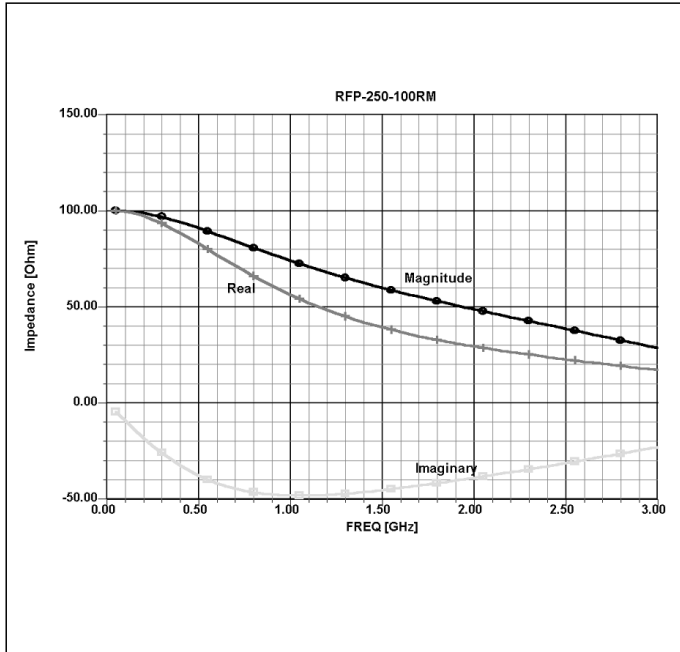
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# Model RFP-250-100RM

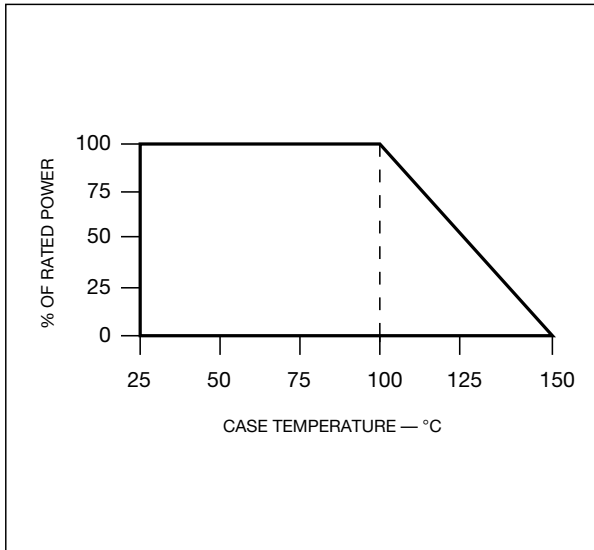


**RF Power**

## Typical Performance



## Power Derating



## Suggested Mounting Procedures

**SUGGESTED STRESS RELIEF METHODS**  
SCALE: ~

**NOT RECOMMENDED APPLICATION**  
SCALE: ~

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Drill & tap the heatsink for the appropriate thread size to be used.
3. Coat heatsink with a minimum amount of high quality silicone grease (.001" max. thickness).
4. Position device on mounting surface and secure using socket head screws, flat & split washers. Torque screws to the appropriate value. Make sure that the device is flat against the heatsink. (Care should be taken to avoid upward pressure of the leads towards the lid).
5. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).